

MEI 720 Die Attacher

Operating Procedures [LINK](#)



Process Description:

Chips, such as capacitors, laser diodes, diodes, IC's, and LED's, or other small components must be attached to empty integrated circuit (IC) package. The die attacher mounts IC chips to the package. A thin film of either a metal or an epoxy is used to weld or glue the chip to the package. This process may involve heat, gas and/or ultrasonic to adhere the die to a package.

Equipment Description:

The MEI 720 is designed for eutectic die attach of IC's, transistors, and other small components to substrates or packages. The system has both mechanical and ultrasonic scrubbing. The hot gas head and the work stage are capable of 500°C. The chip dish is a 2-inch diameter mirror dish with a slide travel of three inches. The process gas available is 2% hydrogen balanced in nitrogen.

<i>Gases Available</i>	
2% Hydrogen bal. Nitrogen	